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LAW OFFICES OF
SYNNESTVEDT & LECHNER
2600 ARAMARK TOWER
1101 MARKET STREET
PHILADELPHIA, PA 19107-2950
TELEPHONE (215) 923-4466
FACSIMILE (215) 923-2189
E-MAIL synnlech@synnlech.com
www.synnlech.com

July 31, 2002

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re\ Application of: Brian Keenan

Appln. No.: 09/674,688

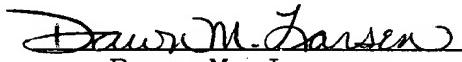
Based on PCT/AU99/00328
Filed May 4, 1999

For: INSULATION MODULE, SYSTEM AND
METHOD FOR INSTALLATION AND
MANUFACTURE

(Atty. Docket No. 24524 USA)

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first-class mail, postage prepaid, in an envelope addressed to: Commissioner for Patents, Washington, DC 20231 on July 31, 2002.


Dawn M. Larsen

SUPPLEMENTAL INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 CFR 1.97(b)

Commissioner for Patents
Washington, DC 20231

Sir:

Applicant hereby requests that the enclosed information items be considered as part of the examination of the application. A list on Form PTO-1449 is attached hereto. A copy of each information item is enclosed.

Pursuant to 37 CFR 1.98(a)(3), applicant herewith submits a concise explanation of the relevance of the information items not in the English language.

Based upon a review of Figures 1-3, French patent document 2,613,814 (information item AM) discloses a means for insulating a chamber, the insulation means having an outer layer 24 mounted on springs 28 to the wall 10 of the chamber, an insulating layer 20 being interposed between outer layer 24 and wall 10.

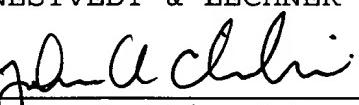
Based upon a review of Figures 1-9, French patent document 2,752,191 (information item AN) discloses a multi-layer composite material for use as insulation.

Based upon a review of Figures 1-3, East German patent document 203,591 (information item AO) discloses an insulative layer attachable to a wall.

Based upon a review of figures 1-6, German patent document 196 31 291 (information item AP) discloses insulating panel assemblies 7 mountable on a surface 4 by means of structural standoffs 26a (see Figure 4) having insulating layers 32 to prevent heat transfer.

Respectfully submitted,

SYNNESTVEDT & LECHNER LLP

By 
John A. Chionchio
Reg. No. 40,954

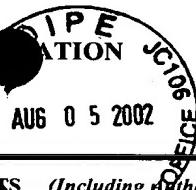
JAC/dml
Enclosures

EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP Section 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.

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INFORMATION DISCLOSURE STATEMENT

(Use several sheets if necessary)



Docket Number (Optional)

24524 USA

Application Number

09/674,688

Applicant(s)

Keenan

Filing Date

2/27/01

Group Art Unit

1772

*EXAMINER
INITIAL

OTHER DOCUMENTS (Including Author, Title, Date, Pertinent Pages, Etc.)

C B	CA	Document Bibliography and Abstract of EP0297612, published January 4, 1989 (Missel GmbH & Co.)
C B	CB	Document Bibliography and Abstract of JP8014483, published January 16, 1996 (Sanyo Electric Co. Ltd.)
C B	CC	Document Bibliography and Abstract of DE3906708, published December 6, 1990 (Partek Corp.; Willich Daemmstoffe & Zubehoer)
C B	CD	Document Bibliography and Abstract of DE4225448, published February 3, 1994 (Janich GmbH & Co.)
C B	CE	Abstract of SU-706271, published December 31, 1979 (Zhdanovtyazhmash)
C B	CF	Abstract of SU1104339, published July 23, 1984 (Andreev VA)
C B	CG	Abstract of SE8804-482-A, published June 13, 1990 (Abb Carbon AB)
C B	CH	Abstract of DE29618681, published October 27, 1996 (W. Hoefer)

EXAMINER

Ch. B.

DATE CONSIDERED

1/14/03

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